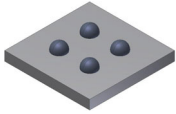


MECHANICAL CASE OUTLINE

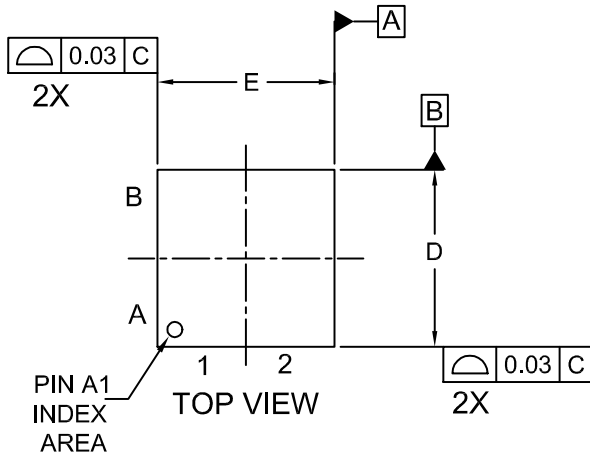
PACKAGE DIMENSIONS

ON Semiconductor®



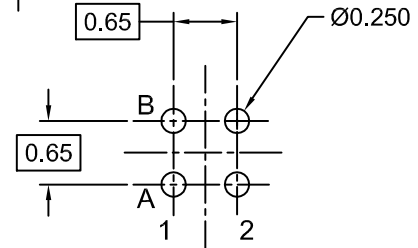
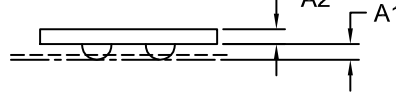
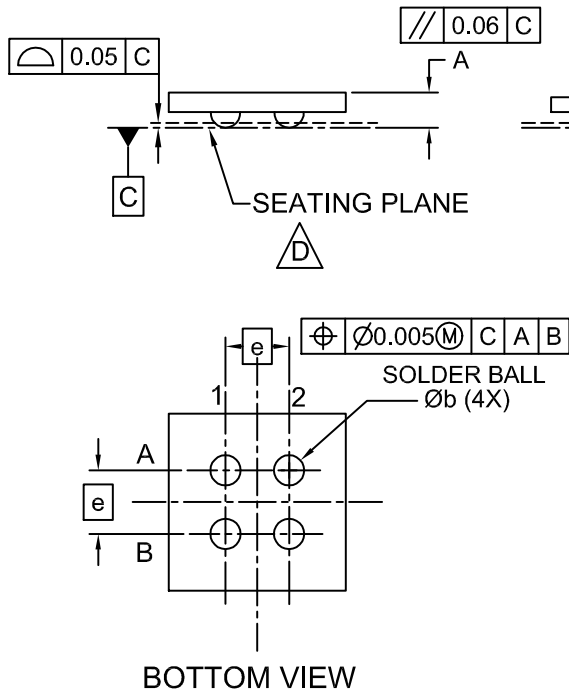
WLCSP4 1.4x1.6x0.35
CASE 567RD
ISSUE A

DATE 04 AUG 2021



- NOTES:
- A. NO JEDEC REGISTRATION APPLIES.
 - B. DIMENSIONS ARE IN MILLIMETERS.
 - C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 1994.
 - \triangle D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
 - E. FOR PIN-OUT ASSIGNMENT, REFER TO DATA SHEET.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	-	-	0.350
A1	0.135	0.160	0.185
A2	0.125	0.150	0.165
b	0.275	0.300	0.325
D	1.35	1.40	1.45
E	1.55	1.60	1.65
e	0.65 BSC		



LAND PATTERN RECOMMENDATION

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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DESCRIPTION:	WLCSP4 1.4x1.6x0.35	PAGE 1 OF 1

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